## LANTRONIX°





# **XPort™ Integration Guide**

Part Number 900-310 Revision G September 2009

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Ethernet is a trademark of XEROX Corporation.

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#### **Disclaimer and Revisions**

Operation of this equipment in a residential area is likely to cause interference, in which case the user, at his or her own expense, will be required to take whatever measures may be required to correct the interference.

**Note:** This product has been designed to comply with the limits for a Class B digital device pursuant to Part 15 of FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy, and if not installed and used in accordance with this guide, may cause harmful interference to radio communications.

Changes or modifications to this device not explicitly approved by Lantronix will void the user's authority to operate this device.

**Note:** With the purchase of XPort, the OEM agrees to an OEM firmware license agreement that grants the OEM a non-exclusive, royalty-free firmware license to use and distribute the binary firmware image provided, only to the extent necessary to use the XPort hardware. For further details, please see the XPort OEM firmware license agreement.

For the latest revision of this product document, please check our online documentation at <u>www.lantronix.com/support/documentation.html.</u>

Date	Rev.	Comments			
11/03	А	Initial Release			
4/04	В	Firmware 1.6 features; information to support XPort-03			
6/04	С	Technical specifications updated			
8/04	D	Firmware 1.8 features; added XPort-485 information			
10/04	Ш	Removed out of date manual references			
3/05	F	Updated illustration			
9/09	G	Updated for release with the new demo board, and XPort-04			

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## 1. Introduction

#### **About the Integration Guide**

This guide provides the information needed to test the XPort<sup>™</sup> device server on the XPort Evaluation Board. This manual is intended for engineers responsible for integrating the XPort into their product.

Note: This document covers XPort<sup>™</sup> Device Server part numbers XP1001000-03R, XP1001001-03R, XP1001000M-03R, XP1002000-03R, XP1002001-03R, XP100200S-03R, XP1001000-04R, XP1001001-04R, XP1001000M-04R, XP1002000-04R, XP1002001-04R, and XP100200S-04R.

#### **Additional Documentation**

The following guides are available on the product CD and the Lantronix Web site (<u>www.lantronix.com</u>)

XPort™ User Guide	Provides information needed to configure, use, and update the XPort firmware.
XPort™ Universal Demo Board Quick Start	Provides the steps for getting the XPort up and running on the demo board.
XPort™ Universal Demo Board User Guide	Provides information needed to use the XPort on the demo board.
DeviceInstaller User Guide	Provides instructions for using the Windows- based utility to configure the XPort and other Lantronix device servers.
Com Port Redirector User Guide	Provides information on using the Windows- based utility to create a virtual com port.

In addition to this documentation, the supplied CD contains a configurable pins control web applet that lets you view the state of the configurable GPIO pins. This applet is provided in the Sample Code and Solutions folder.

For firmware versions 1.3 and earlier, the corresponding applet file is xptcpctl102.cob. For later firmware versions (greater than version 1.3), the corresponding applet file is xpt\_gpioctl\_154.cob.

## 2. Description and Specifications

The XPort embedded device server is a complete network-enabling solution enclosed within an RJ45 package. This miniature serial-to-Ethernet converter empowers original equipment manufacturers (OEMs) to quickly and easily go to market with networking and web page serving capabilities built into their products.

#### **The XPort**

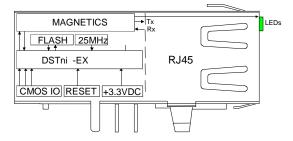
The XPort contains Lantronix's own DSTni controller, with 256 Kbytes of SRAM, 16 Kbytes of boot ROM, and integrated AMD 10/100 PHY.

The XPort also contains the following:

- 3.3-volt serial interface
- All I/O pins are 5V tolerant
- 4-Mbit flash memory
- Ethernet magnetics
- Power supply filters
- Reset circuit
- +1.8V regulator
- 25-MHz crystal and Ethernet LEDs

The XPort requires +3.3-volt power and is designed to operate in an extended temperature range (see technical data).

#### Figure 2-1 Side View of the XPort



#### **XPort Block Diagram**

The following drawing is a block diagram of the XPort showing the relationships of the components.

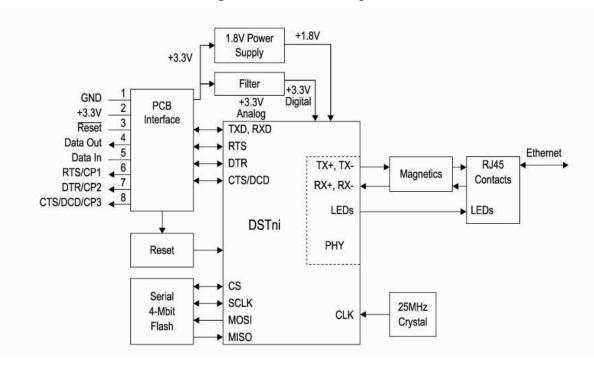


Figure 2-2 XPort Block Diagram

## **PCB Interface**

The XPort has a serial port compatible with data rates up to 920 kbps (in highperformance mode). The serial signals (pins 4–8) are 3.3V CMOS logic level, and 5V tolerant. The serial interface pins include +3.3V, ground, and reset. The serial signals usually connect to an internal device, such as a UART. For applications requiring an external cable running with RS-232 or RS422/485 voltage levels, the XPort must interface to a serial transceiver chip.

Signal Name	XPort Pin #	Primary Function	
GND	1	Circuit ground	
3.3V	2	+3.3V power in	
Reset	3	External reset in	
Data Out	4	Serial data out (driven by DSTni's built-in UART)	
Data In	5	Serial data in (read by DSTni's built-in UART)	
CP1/RTS (Configurable Pin 1)	6	<ul> <li>CP1 can be configured as follows:</li> <li>Flow control: RTS (Request to Send) output driven by DSTni's built-in UART for connection to CTS of attached device.</li> </ul>	
		<ul> <li>Programmable input/output: CP1 can be driven or read through software control, independent of serial port activity.</li> </ul>	

#### **Table 2-1 PCB Interface Signals**

Signal Name	XPort Pin #	Primary Function
CP2/DTR (Configurable Pin 2)	7	<ul> <li>CP2 can be configured as follows:</li> <li>Modem control: DTR (Data Terminal Ready) output driven by DSTni's built-in UART for connection to DCD of attached device.</li> <li>Programmable input/output: CP2 can be driven or read through software control, independent of serial port activity.</li> </ul>
CP3/CTS/DCD (Configurable Pin 3)	8	<ul> <li>CP3 can be configured as follows:</li> <li>Flow control: CTS (Clear to Send) input read by DSTni's built-in UART for connection to RTS of attached device.</li> <li>Modem control: DCD (Data Carrier Detect) input read by DSTni's built-in UART for connection to DTR of attached device.</li> <li>Programmable input/output: CP3 can be driven or read through software control, independent of serial port activity.</li> </ul>

## **Ethernet Interface**

The Ethernet interface magnetics, RJ45 connector, and Ethernet status LEDs are all in the device server shell.

Signal Name	DIR	Contact	Primary Function		
TX+	Out	1	Differential Ethernet transmit data +		
TX- Out 2		2	Differential Ethernet transmit data -		
RX+ In 3 Differential Ethernet receive data +		Differential Ethernet receive data +			
RX- In 6		6	Differential Ethernet receive data -		
Not used		4	Terminated		
Not used		5	Terminated		
Not used		7	Terminated		
Not Used		8	Terminated		
SHIELD			Chassis ground		

#### Table 2-2 Ethernet Interface Signals (Industry Standards)

## **LEDs**

The XPort contains the following LEDs:

- Link (bi-color, left LED)
- Activity (bi-color, right LED)

# CONTACT 8 SHIELD TAB

Figure 2-3 XPort LEDs

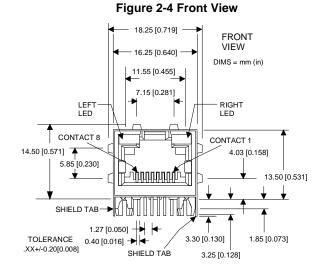
#### Table 2-3 XPort LED Functions

Link LED Left Side					
Color Meaning					
Off	No Link				
Amber	10 Mbps				
Green	100 Mbps				

Activity LED Right Side					
Color Meaning					
Off	No Acti∨ity				
Amber	Half Duplex				
Green	Full Duplex				

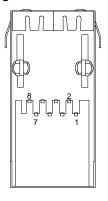


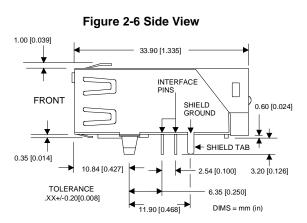
## **Dimensions**



The XPort dimensions are shown in the following drawings.

Figure 2-5 Bottom View





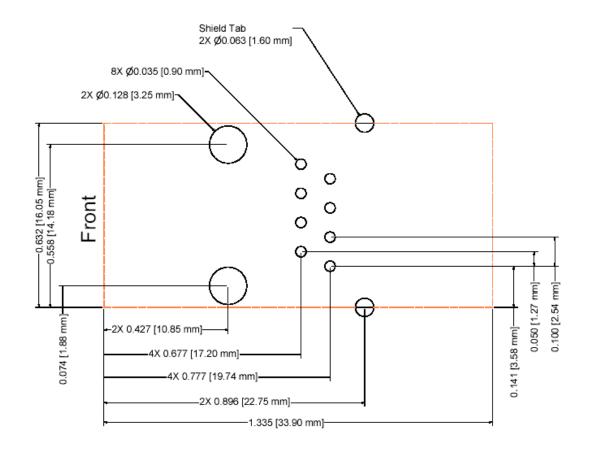
#### **Recommended PCB Layout**

The hole pattern and mounting dimensions for the XPort device server are shown in the following drawing. For proper heat dissipation, it is recommended that the PCB have approximately 1 square inch of copper attached to the shield tabs. The shield tabs are an important source of heat sinking for the device.

The XPort shield is considered "chassis ground" and should be separate from "signal ground". ESD near the XPort at the panel opening will likely jump to the shield.

We recommend using high voltage (~200V), low ESR, 0.01uF capacitors to connect chassis ground to both signal ground and 3.3V. This will cause any voltage spike from ESD to be imparted equally to both signal ground and 3.3V with no net voltage increase between 3.3V and signal ground. For the highest level of ESD protection of the XPort, it is recommended that the shield not be directly connected to signal GND. The metal shield fingers around the XPort's RJ45 should physically contact the product housing when the housing is metal, or metallic coated.

The shield is also a heat sink for the internal EX Processor. As in all heat sinking applications, the more copper connected to the heat sink the better. Adding 1 inch square inch of copper flood on the PCB is adequate to allow the XPort to work up to +85°C. If the application does not expect to see t emperatures up to +85°C the heat sink may be smaller than 1 square inch.



#### Figure 2-7 PCB Layout

## **Product Information Label**

The product information label contains important information about your specific unit, such as its product ID (name), bar code, part number, and Ethernet (MAC) address.

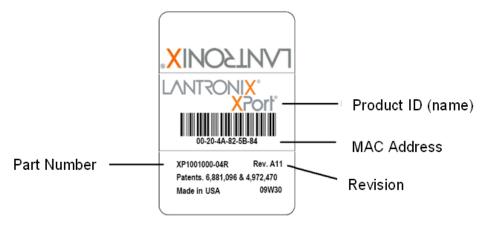


Figure 2-8 Product Label

## **Electrical Specifications**

<u>CAUTION:</u> Stressing the device above the rating listed in Table 2-4 may cause permanent damage to the XPort. Exposure to Absolute Maximum Rating conditions for extended periods may affect the XPort's reliability.

Parameter	Symbol	Min	Max	Units
Supply Voltage	V <sub>CC</sub>	0	3.6	Vdc
CPx, Data In, Data Out Voltage	V <sub>CP</sub>	-0.3	6	Vdc
Operating Temperature		-40	85	°C
Storage Temperature		-40	85	°C

Parameter	Symbol	Min	Typical	Max	Units
Supply Voltage	V <sub>CC</sub>	3.15	3.3	3.46	Vdc
Supply Voltage Ripples	V <sub>CC_PP</sub>			2	%
Supply Current(typ normal	I <sub>CC</sub>		224		mA
CPU speed)					
Power Reset threshold		2.7			Vdc
RESET pin Input low Voltage	V <sub>RES_IL</sub>			0.36	Vdc
RESET pin Input High	V <sub>RES_IL</sub>	1.4		3.6	Vdc
Voltage					
CPx, RX	V <sub>CP_IL</sub>			0.8	Vdc
Input Low Voltage					
CPx, RX	V <sub>CP_IH</sub>	2		5.5	Vdc
Input High Voltage					
CPx, TX Output Low Voltage	V <sub>CP_OL</sub>			0.4	Vdc
CPx, TX Output High Voltage	V <sub>CP_OH</sub>	2.4			Vdc

#### **Table 2-5 Recommended Operating Conditions**

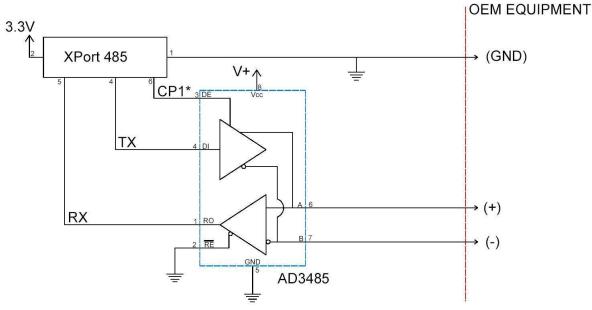
## **Technical Specifications**

Category	Description				
CPU, Memory	Lantronix DSTni-EX 186 CPU, 256-Kbyte zero wait state SRAM, 512-Kbyte flash, 16-Kbyte boot ROM				
Firmware	Upgradeable via TFTP and serial port				
Reset Circuit	Internal 200ms power-up reset pulse. Power-drop reset triggered at 2.6V. External reset input causes an internal 200ms reset.				
Serial Interface	CMOS (Asynchronous) 3.3V-level signals Rate is software selectable: 300 bps to 921600 bps				
Serial Line Formats	Data bits: 7 or 8 Stop bits: 1 or 2 Parity: odd, even, none				
Modem Control	DTR/DCD, CTS, RTS				
Flow Control	XON/XOFF (software), CTS/RTS (hardware), None				
Programmable I/O	3 PIO pins (software selectable), sink or source 4mA max.				
Network Interface	RJ45 Ethernet 10Base-T or 100Base-TX (auto-sensing)				
Compatibility	Ethernet: Version 2.0/IEEE 802.3 (electrical), Ethernet II frame type				
Protocols Supported	ARP, UDP/IP, TCP/IP, Telnet, ICMP, SNMP, DHCP, BOOTP, TFTP, Auto IP, SMTP, and HTTP				
LEDs	10Base-T and 100Base-TX Link Activity, Full/half duplex. Software generated status & diagnostic signals can optionally drive external LEDs through CP1 & CP3.				
Management	Internal web server, SNMP (read only) Serial login, Telnet login				
Security	Password protection, locking features, optional Rijndael 256-bit encryption				
Internal Web Server	Serves static web pages and Java applets Storage capacity: 384 Kbytes				
Weight	0.34 oz (9.6 grams)				
Material	Metal shell, thermoplastic case				
Temperature	Operating range: -40℃ to +85℃ (-40뚜 to 185뚜) normal mode, -40℃ to +75℃ (-40뚜 to 167뚜) high-performance mode				
Shock/Vibration	Non-operational shock: 500 g's Non-operational vibration: 20 g's				
Warranty	Two year limited warranty				
Included Software	Windows <sup>™</sup> 98/NT/2000/XP-based Device Installer configuration software and Windows <sup>™</sup> -based Com Port Redirector				
EMI Compliance	Radiated and conducted emissions - complies with Class B limits of EN 55022:1998 Direct & Indirect ESD - complies with EN55024:1998 RF Electromagnetic Field Immunity - complies with EN55024:1998 Electrical Fast Transient/Burst Immunity - complies with EN55024:1998 Power Frequency Magnetic Field Immunity - complies with EN55024:1998 RF Common Mode Conducted Susceptibility - complies with EN55024:1998				

#### Table 2-6 Technical Specification

## A: RS422/485 Connection Diagram

The following example illustrates a connection between the XPort-485 to an external transceiver IC:



\* Any one of CP1, CP2 or CP3 can be used to control the TX enable.

## **B: Compliance**

(According to ISO/IEC Guide 22 and EN 45014)

#### Manufacturer's Name & Address:

Lantronix 15353 Barranca Parkway, Irvine, CA 92618 USA Declares that the following product: Product Name Model: XPort Embedded Device Server

Conforms to the following standards or other normative documents:

#### **Electromagnetic Emissions:**

EN55022: 1998 (IEC/CSPIR22: 1993) Radiated RF emissions, 30MHz-1000MHz Conducted RF Emissions – Telecom Lines – 150 kHz – 30 MHz FCC Part 15, Subpart B, Class B IEC 1000-3-2/A14: 2000

IEC 1000-3-3: 1994

#### **Electromagnetic Immunity:**

EN55024: 1998 Information Technology Equipment-Immunity Characteristics Direct ESD, Contact Discharge Indirect ESD Radiated RF Electromagnetic Field Test Electrical Fast Transient/Burst Immunity RF Common Mode Conducted Susceptibility Power Frequency Magnetic Field Test Manufacturer's Contact:

Lantronix 15353 Barranca Parkway, Irvine, CA 92618 USA Tel: (800) 526-8766 Tel: (949) 453-3990 Fax: (949) 450-7249

#### **RoHS Notice:**

All Lantronix products in the following families are China RoHS-compliant and free of the following hazardous substances and elements:

- Lead (Pb) Cadmium (Cd) •
- Mercury (Hg) Hexavalent Chromium (Cr (VI)) • ٠
- •
- Polybrominated biphenyls (PBB) Polybrominated diphenyl ethers (PBDE) ٠

Product Family Name	Toxic or hazardous Substances and Elements						
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr (VI))	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)	
UDS1100 and 2100	0	0	0	0	0	0	
EDS	0	0	0	0	0	0	
MSS100	0	0	0	0	0	0	
IntelliBox	0	0	0	0	0	0	
XPress DR & XPress-DR+	0	0	0	0	0	0	
SecureBox 1101 & 2101	0	0	0	0	0	0	
WiBox	0	0	0	0	0	0	
UBox	0	0	0	0	0	0	
MatchPort	0	0	0	0	0	0	
SLC	0	0	0	0	0	0	
XPort	0	0	0	0	0	0	
WiPort	0	0	0	0	0	0	
SLB	0	0	0	0	0	0	
SLP	0	0	0	0	0	0	
SCS	0	0	0	0	0	0	
SLS	0	0	0	0	0	0	
DSC	0	0	0	0	0	0	

O: toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.

## C: Warranty

For details on the Lantronix warranty replacement policy, go to our web site at <u>www.lantronix.com/support/warranty</u>.